

ABSTRACT OF THE DISCLOSURE

POLISHING APPARATUS, POLISHING METHOD AND METHOD FOR OUTPUTTING VISUALIZATION INFORMATION 5 OF FILM THICKNESS DISTRIBUTION ON SUBSTRATE

A polishing apparatus capable of acquiring accurate film thickness distribution information is disclosed. The polishing apparatus includes a polishing table, a plurality of film thickness sensors, and a controller. The controller analyzes film thickness distribution
10 information of a substrate while identifying a notch position of the substrate based on the measured film thickness information, and outputs visualization information of the film thickness distribution with the notch position as a reference position.

FIG. 6